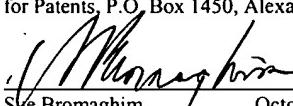
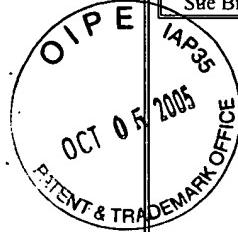


Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on October 3, 2005.

  
Sue Bromaghim

October 3, 2005



**CUSTOMER NO. 36257**

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Wayne Glenn Renken

Title: System and Method for Heating and Cooling Wafer at Accelerated Rates

Application No.: 10/619,731 Filing Date: July 15, 2003

Examiner: Dhingra, Rakesh Kumar Group Art Unit: 1763

Docket No.: SENS.007US1 Conf. No.: 7022

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

Pursuant to 37 C.F.R. §§ 1.56, 1.97 and 1.98, Applicant(s) call(s) the documents listed on the enclosed Form PTO-1449 to the Examiner's attention in this patent application.

- According to 37 C.F.R. 1.98(2)(ii), copies of the U.S. Patents and U.S. Published Copies of the listed foreign patent documents or Other Art are enclosed.

Citation of these documents shall not be construed as (1) an admission that the documents are prior art with respect to the invention or inventions claimed in this application, (2) a representation that a search has been made (other than as indicated by any cited document), or

Attorney Docket No.: SENS.007US1

Application No.: 10/619,731

(3) an admission that the cited information is, or is considered to be, material to patentability as defined in § 1.56(b).

This information disclosure statement is submitted under 37 C.F.R. § 1.97(c). The fee authorization for \$180.00 for the information disclosure statement fee under 37 C.F.R. § 1.17(p), is enclosed.

Respectfully submitted,

*Peter Gallagher* 10/3/05  
Peter A. Gallagher      Date  
Reg. No. 47,584

U.S. Department of Commerce, Patent and Trademark		Atty. Docket No.	Application No.
INFORMATION DISCLOSURE STATEMENT BY APPLICANT		SENS.007US1	10/619,731
		Applicant(s)	Conf. No.
(Use several sheets if necessary)		Wayne Glenn RENKEN	7022
(Form PTO-1449) OCT 05 2005		Filing Date	Art Group
		July 15, 2003	1763

**U.S. Patent Documents**

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
1	4,685,331	08-1987	RENKEN et al.			
2	5,670,218	09-1997	BAEK			
3	6,494,955	12-2002	LEI et al.			

**U.S. Published Patent Application Documents**

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate

**Foreign Patent Documents**

						Translation		
		Document	Date	Country	Class	Subclass	Yes	No

**OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)**

4	Smith et al., "Modeling the impact of thermal history during post exposure bake on the lithographic performance of chemically amplified resists", Proceeding of the SPIE, Vol. 4345, pp. 1013-1021 (2001), Advances in Resist Technology and Processing XVIII.					

Examiner \_\_\_\_\_ Date Considered \_\_\_\_\_

**\*EXAMINER:** Initial if reference considered, whether or not citation is in-conformance with MPEP-609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.